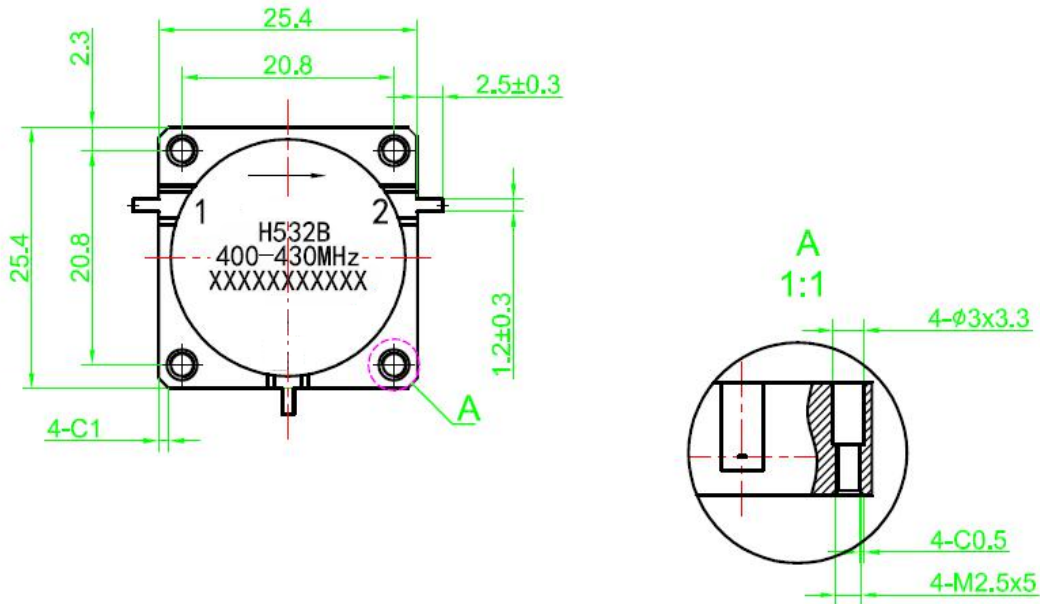


1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

Part No.	Frequency (GHz)		Center Frequency (GHz)	Bandwidth (GHz)	Isolation (dB) MIN	INS LOSS (dB) MAX	VSWR (dB) MAX	Power (W)	IMD (@2X43dBm) (-dBc) MAX
	F1	F2							
H532B [400-430]MHz	0.400	0.430	0.4150	0.030	20	0.4	1.22	200	
H532B [566-600] MHz	0.566	0.600	0.5830	0.034	23	0.25	1.15	200	
H532B [566-678]MHz	0.566	0.678	0.6215	0.112	18	0.45	1.28	200	
H532B [600-684]MHz	0.600	0.684	0.6420	0.084	20	0.35	1.2	100	
H532B [600-700]MHz	0.600	0.700	0.6500	0.100	23	0.35	1.15	200	-65
H532B [700-740]MHz	0.700	0.740	0.7200	0.040	22	0.22	0.25	100	-70
H532B [758-803]MHz	0.758	0.803	0.7805	0.045	25	0.2	1.12	250	-70
H532B [925-960]MHz	0.925	0.960	0.9425	0.035	25	0.2	1.12	250	-75
H532B [1805-1880]MHz	1.805	1.880	1.838	0.075	23	0.25	1.15	300	-75
H532B [1930-1995]MHz	1.930	1.995	1.963	0.075	23	0.25	1.15	300	-75
H532B [2110-2170]MHz	2.110	2.170	2.140	0.060	25	0.2	1.12	250	-75